



ALPHA & OMEGA
SEMICONDUCTOR

AON6250

150V N-Channel MOSFET

General Description

The AON6250 uses trench MOSFET technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$, C_{iss} and C_{oss} . This device is ideal for boost converters and synchronous rectifiers for consumer, telecom, industrial power supplies and LED backlighting.

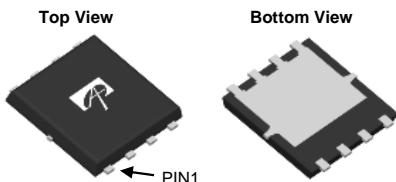
Product Summary

| | |
|---------------------------------|----------|
| V_{DS} | 150V |
| I_D (at $V_{GS}=10V$) | 52A |
| $R_{DS(ON)}$ (at $V_{GS}=10V$) | < 16.5mΩ |
| $R_{DS(ON)}$ (at $V_{GS}=6V$) | < 19mΩ |

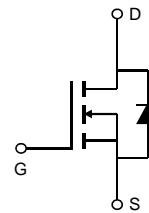
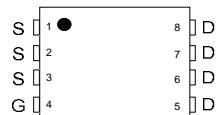
100% UIS Tested
100% R_g Tested



DFN5x6



Top View



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

| Parameter | Symbol | Maximum | Units |
|---|----------------|------------|-------|
| Drain-Source Voltage | V_{DS} | 150 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current | I_D | 52 | A |
| Current $T_c=100^\circ C$ | | 32 | |
| Pulsed Drain Current ^C | I_{DM} | 112 | A |
| Continuous Drain Current | I_{DSM} | 13.5 | A |
| $T_A=70^\circ C$ | | 10.5 | |
| Avalanche Current ^C | I_{AS} | 33 | A |
| Avalanche energy $L=0.3mH$ ^C | E_{AS} | 163 | mJ |
| Power Dissipation ^B | P_D | 104 | W |
| $T_c=100^\circ C$ | | 41.5 | |
| Power Dissipation ^A | P_{DSM} | 7.4 | W |
| $T_A=70^\circ C$ | | 4.7 | |
| Junction and Storage Temperature Range | T_J, T_{STG} | -55 to 150 | °C |

Thermal Characteristics

| Parameter | Symbol | Typ | Max | Units |
|---|-----------|-----|-----|-------|
| Maximum Junction-to-Ambient ^A | $R_{θJA}$ | 14 | 17 | °C/W |
| Maximum Junction-to-Ambient ^{A,D} Steady-State | | 40 | 55 | °C/W |
| Maximum Junction-to-Case | $R_{θJC}$ | 1 | 1.2 | °C/W |

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|-----------------------------|---------------------------------------|--|------|------|----------|------------------|
| STATIC PARAMETERS | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $I_D=250\mu\text{A}, V_{GS}=0\text{V}$ | 150 | | | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=150\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$ | | | 1 | μA |
| I_{GSS} | Gate-Body leakage current | $V_{DS}=0\text{V}, V_{GS}=\pm20\text{V}$ | | | ±100 | nA |
| $V_{\text{GS(th)}}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}, I_D=250\mu\text{A}$ | 2.4 | 2.85 | 3.4 | V |
| $I_{\text{D(ON)}}$ | On state drain current | $V_{GS}=10\text{V}, V_{DS}=5\text{V}$ | 112 | | | A |
| $R_{\text{DS(ON)}}$ | Static Drain-Source On-Resistance | $V_{GS}=10\text{V}, I_D=20\text{A}$ $T_J=125^\circ\text{C}$ | 13.5 | 16.5 | | $\text{m}\Omega$ |
| | | $V_{GS}=6\text{V}, I_D=20\text{A}$ | 27.4 | 33.5 | | |
| g_{FS} | Forward Transconductance | $V_{DS}=5\text{V}, I_D=20\text{A}$ | 58 | | | S |
| V_{SD} | Diode Forward Voltage | $I_S=1\text{A}, V_{GS}=0\text{V}$ | 0.69 | 1 | | V |
| I_S | Maximum Body-Diode Continuous Current | | | | 52 | A |
| DYNAMIC PARAMETERS | | | | | | |
| C_{iss} | Input Capacitance | $V_{GS}=0\text{V}, V_{DS}=75\text{V}, f=1\text{MHz}$ | | 2388 | | pF |
| C_{oss} | Output Capacitance | | | 213 | | pF |
| C_{rss} | Reverse Transfer Capacitance | | | 9.5 | | pF |
| R_g | Gate resistance | $V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$ | 0.4 | 0.95 | 1.5 | Ω |
| SWITCHING PARAMETERS | | | | | | |
| Q_g | Total Gate Charge | $V_{GS}=10\text{V}, V_{DS}=75\text{V}, I_D=20\text{A}$ | | 30.5 | 43 | nC |
| Q_{gs} | Gate Source Charge | | | 10.5 | | nC |
| Q_{gd} | Gate Drain Charge | | | 4.5 | | nC |
| $t_{\text{D(on)}}$ | Turn-On Delay Time | $V_{GS}=10\text{V}, V_{DS}=75\text{V}, R_L=3.75\Omega, R_{\text{GEN}}=3\Omega$ | | 11 | | ns |
| t_r | Turn-On Rise Time | | | 3 | | ns |
| $t_{\text{D(off)}}$ | Turn-Off Delay Time | | | 23 | | ns |
| t_f | Turn-Off Fall Time | | | 4.5 | | ns |
| t_{rr} | Body Diode Reverse Recovery Time | $I_F=20\text{A}, dI/dt=500\text{A}/\mu\text{s}$ | | 68 | | ns |
| Q_{rr} | Body Diode Reverse Recovery Charge | $I_F=20\text{A}, dI/dt=500\text{A}/\mu\text{s}$ | | 560 | | nC |

A. The value of R_{JJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The Power dissipation P_{DSM} is based on $R_{\text{JJA}}, t \leq 10\text{s}$ and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{C}$.

D. The R_{JJA} is the sum of the thermal impedance from junction to case R_{JJC} and case to ambient.

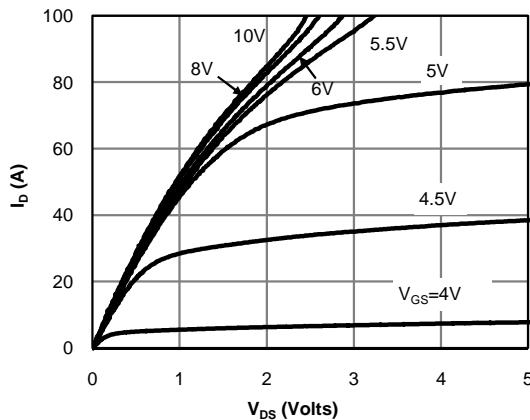
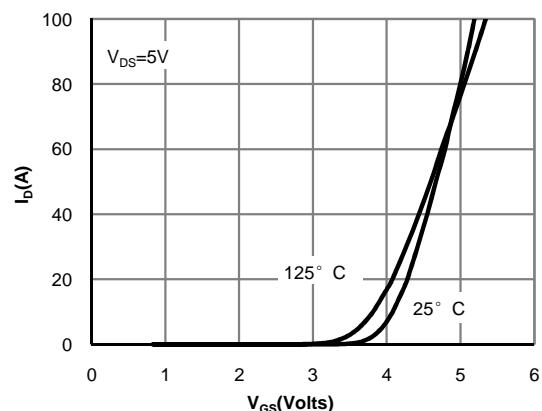
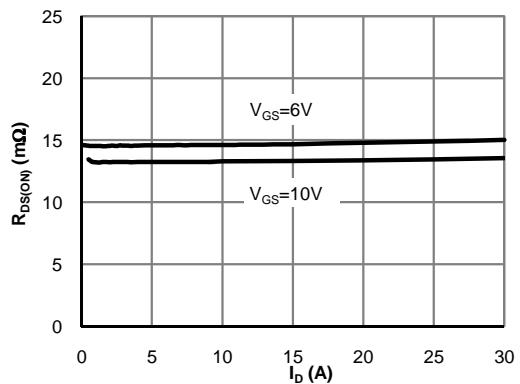
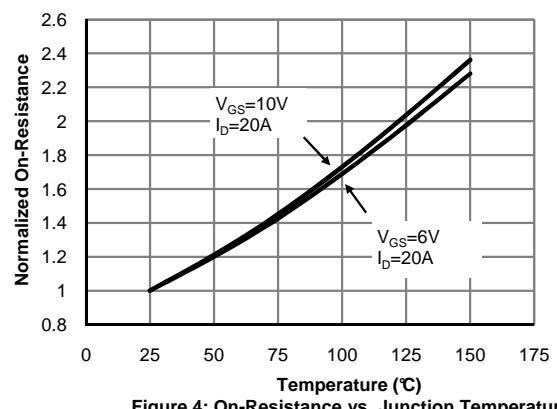
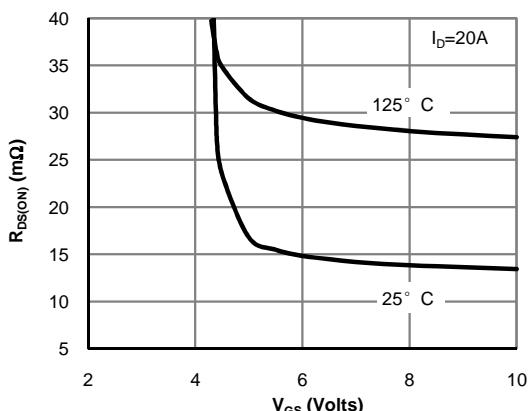
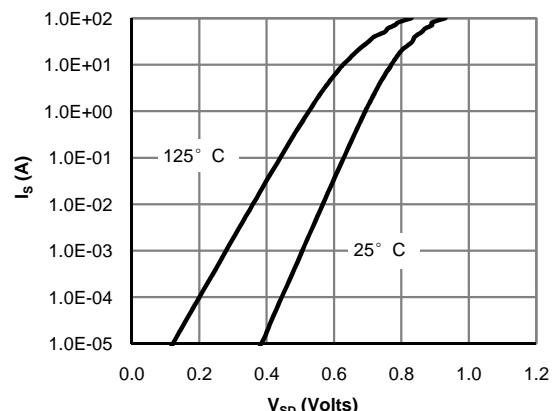
E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

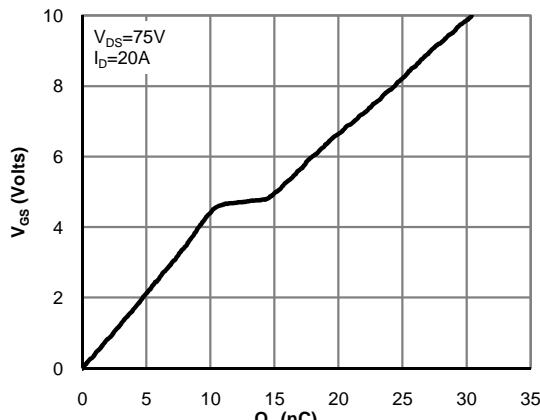
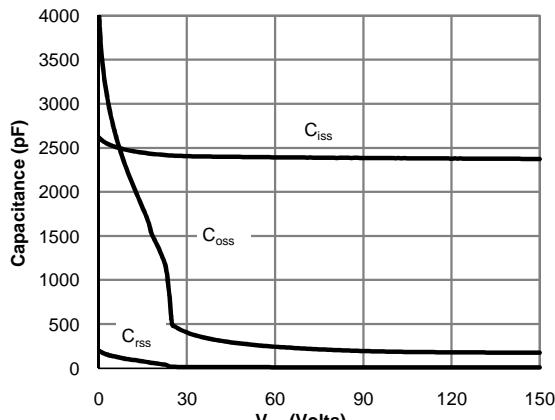
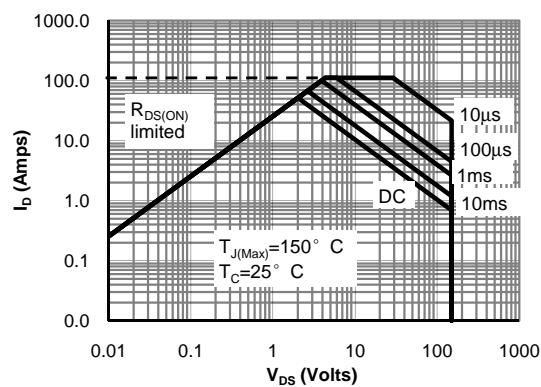
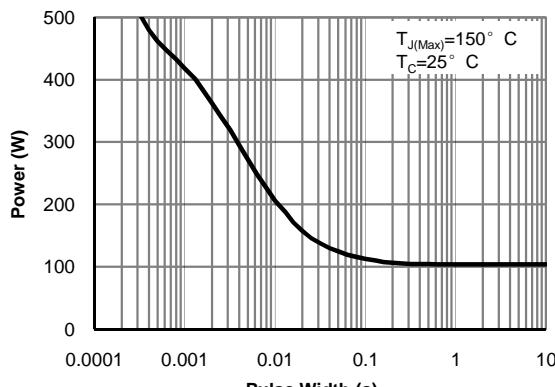
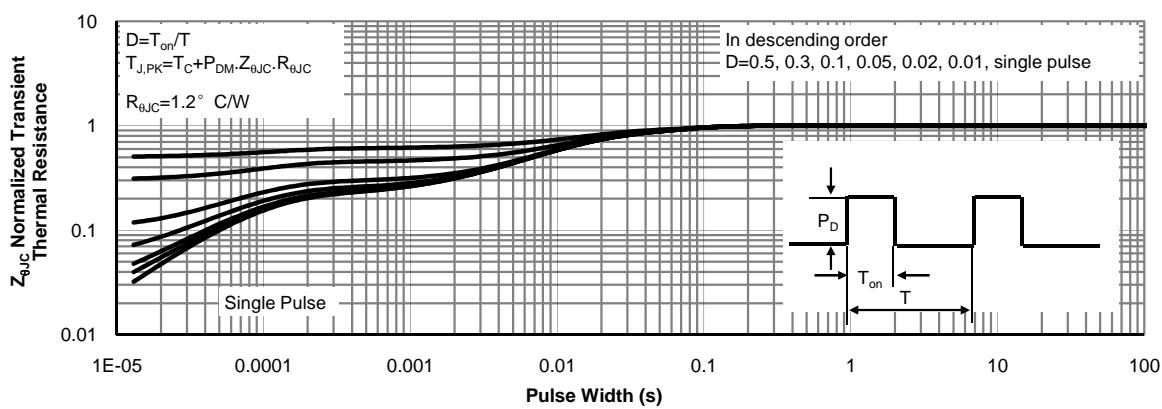
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(\text{MAX})}=150^\circ\text{C}$. The SOA curve provides a single pulse rating.

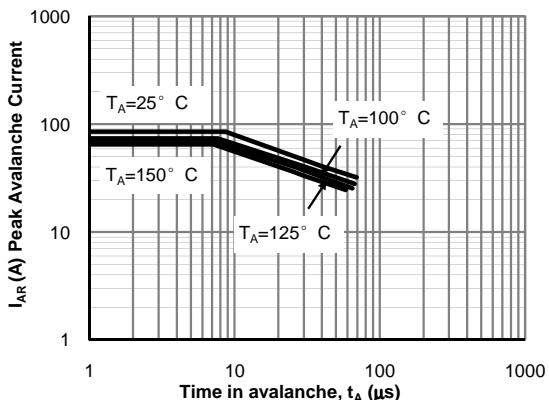
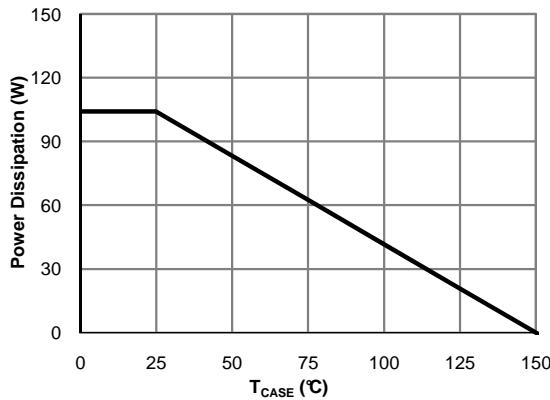
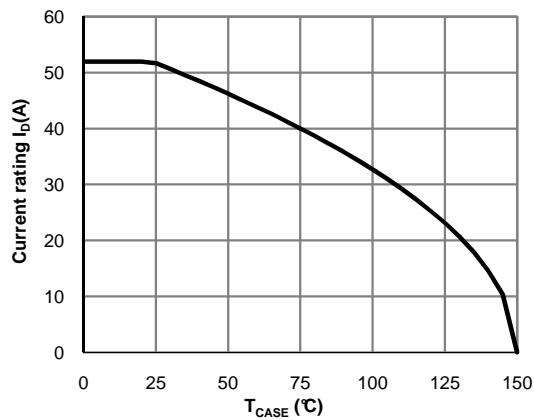
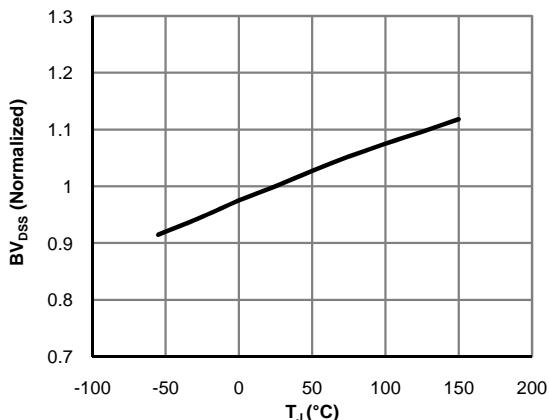
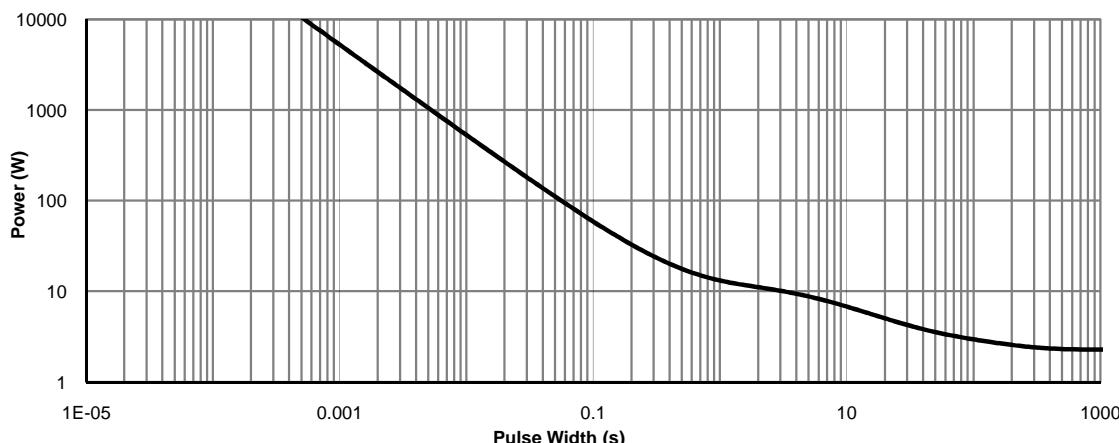
G. The maximum current rating is package limited.

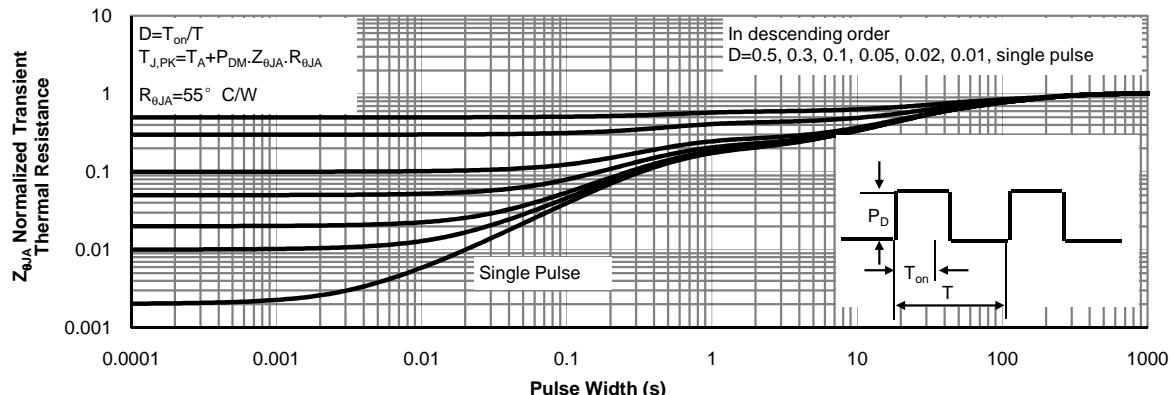
H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$.

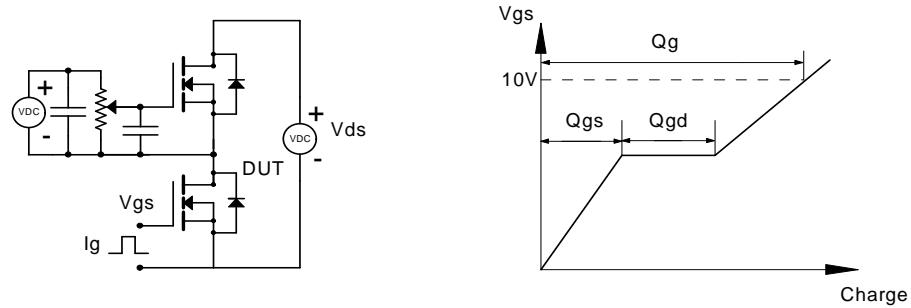
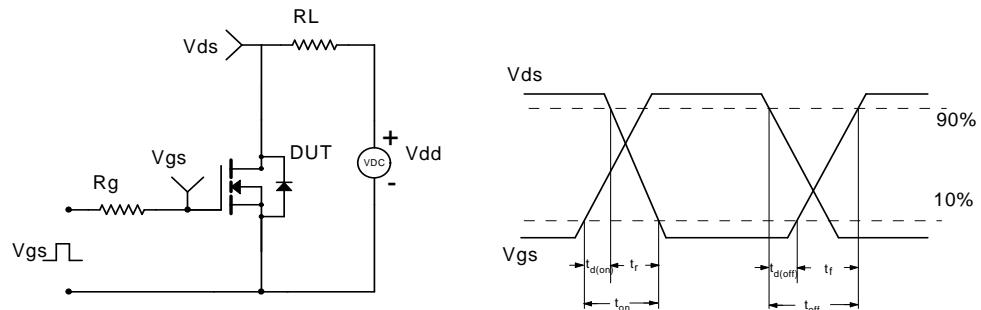
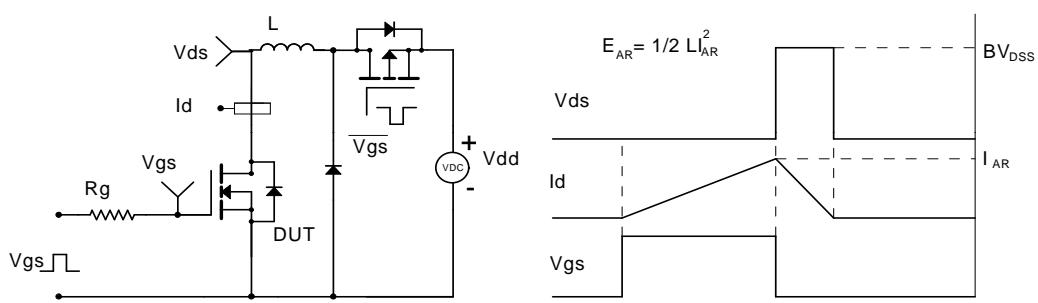
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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Fig 1: On-Region Characteristics (Note E)

Figure 2: Transfer Characteristics (Note E)

Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

Figure 4: On-Resistance vs. Junction Temperature (Note E)

Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 12: Single Pulse Avalanche capability (Note C)

Figure 13: Power De-rating (Note F)

Figure 14: Current De-rating (Note F)

Figure 15: Break Down vs. Junction Temperature

Figure 16: Single Pulse Power Rating Junction-to-Ambient (Note H)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 17: Normalized Maximum Transient Thermal Impedance (Note H)

Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

Diode Recovery Test Circuit & Waveforms
